

ABSTRACT

A digital image capture system includes an image sensor, a package structure for holding the image sensor, and electrical connectors for creating electrical connections
5 between the image sensor and a circuit board. The package structure includes attachment features that enable an optics system to be securely attached to the package structure after the package structure has been soldered to the circuit board. In an embodiment, the attachment features align the optics system with the image sensor without having to power up the image sensor. An embodiment of the attachment
10 features includes mechanical attachment features, such as clip arms and/or clip receivers. In an embodiment, the optics system includes attachment features that are complementary to the attachment features of the package structure. The package structure and optics system may additionally include complementary contact surfaces that create a light-tight connection between the optics system and the package
15 structure.

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